

ETSI EN 301 605 V1.1.1 (2013-10)



**Environmental Engineering (EE);
Earthing and bonding of 400 VDC data and
telecom (ICT) equipment**

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Contents

Intellectual Property Rights	5
Foreword.....	5
Introduction	6
1 Scope	7
2 References	7
2.1 Normative references	7
2.2 Informative references.....	8
3 Definitions and abbreviations.....	9
3.1 Definitions.....	9
3.1.1 IEC definitions.....	9
3.1.2 Other definitions	10
3.2 Abbreviations	11
4 General requirements	12
4.1 Safety from electrical hazards	12
4.2 Signal reference.....	13
4.3 EMC performance	13
5 Requirements on bonding networks.....	13
5.1 Bonding configurations	13
5.2 CBN within a building for data and telecom centres.....	13
5.3 BN within a data and telecom centre.....	14
5.4 Merging of CBN and MESH-BNs	16
5.5 Cabling within and between BNs	16
6 Requirements for power distribution.....	16
6.1 DC power distribution of secondary supply	16
6.1.1 General.....	16
6.1.2 System earthing arrangement.....	16
6.1.2.1 IT system with earthed high-ohmic mid-point (MP) terminal	17
6.1.2.2 TN-S system with earthed negative line terminal (L-)	18
6.2 DC power distribution of tertiary supplies	19
6.3 AC mains distribution and bonding of the protective conductor	20
6.4 AC power distribution from tertiary power supply	20
Annex A (normative): Rationale about CBN co-ordination.....	21
Annex B (normative): Requirements for fault protection.....	22
B.1 Protective earthing.....	22
B.1.1 TN and TT System Earthing.....	22
B.1.2 IT System Earthing.....	22
B.1.2.1 First fault on one of the live conductors	22
B.1.2.2 Second fault on a different live conductor	23
B.2 Protective equipotential bonding.....	24
Annex C (informative): Coexistence of -48 VDC/-60 VDC DC-C (2-wire) and 400 VDC class I equipment in MESH-BN	25
Annex D (informative): Conductor arrangement and system earthing	27
D.1 General remarks	30
D.2 Ease of earth fault detection with high ohmic mid-point	31
D.2.1 IT system with (L-) earthed via high impedance	31
D.2.2 IT system with earthed high-ohmic mid-point (MP) terminal.....	31

D.3	Impact on body current due to a large number of loads	32
Annex E (normative):	AC mains distribution and bonding of the protective conductor	34
Annex F (normative):	Basic protection and Fault protection.....	37
F.1	Basic protection (protection against direct contact)	37
F.1.1	Basic insulation of live parts	37
F.2	Fault protection (protection against indirect contact).....	37
F.2.1	Automatic disconnection in case of a fault.....	37
F.3	Conclusions	38
Annex G (informative):	Bibliography.....	39
History		40

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Foreword

This European Standard (EN) has been produced by ETSI Technical Committee Environmental Engineering (EE).

The present document has been produced within the framework of the following considerations:

- a) Datacommunications and Telecommunications (ICT) equipment is generally installed in data and telecom centres and held in racks, cabinets or other mechanical structures;
- b) the existing ITU-T and ITU-R Recommendations and CENELEC standards in such matters do not ensure the required standardization at the equipment level;
- c) network operators and equipment providers agreed to standardize on a bonding configuration that facilitates:
 - compliance with functional requirements including Electromagnetic Compatibility (EMC) aspects of emission and immunity;
 - compatible building and equipment provisions;
 - installation of new data and telecom centres as well as expansion or replacement of installations in existing data and telecom centres with equipment coming from different suppliers;
 - a structured installation practice;
 - simple maintenance rules;
 - contracting on a common basis;
 - cost effectiveness in development, manufacturing, installation and operation.

National transposition dates

Date of adoption of this EN:	30 September 2013
Date of latest announcement of this EN (doa):	31 December 2013
Date of latest publication of new National Standard or endorsement of this EN (dop/e):	30 June 2014
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Introduction

The present document addresses earthing and bonding of data and telecom (ICT) equipment in data and telecom centres when implementing a direct current interface up to 400 VDC defined in EN 300 132-3-1 [1] in relation to safety, functional performance and EMC. The present standard may also be applicable for ICT equipment in other locations such as: street cabinets, containers, subscriber's buildings, BTSs, etc.

The general principles for electrical installations from a safety perspective are based on the HD 60364-series (IEC 60364-series) of standards, and where appropriate on information published by ITU-T to provide for the proper functioning of those installations.

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